

为您的产品保驾护航

PRODUCT DATASHEET

PTC Devices · Surface Mount

**JFC0402FS Series Fuse**



### Description

JFC0402FS Series Chip fuses set the industry standard for performance, reliability and quality. The solder-free design provides excellent on-off and temperature cycling characteristics and also makes our chip fuses more heat and shock tolerant than typical subminiature fuses.

### Features

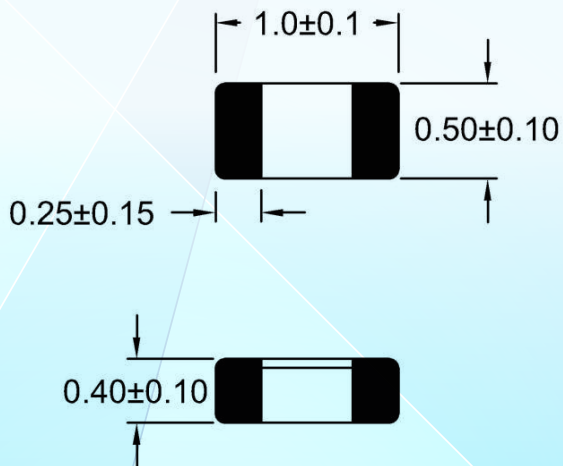
- Fast acting for excessive current
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material

### Electrical Characteristics

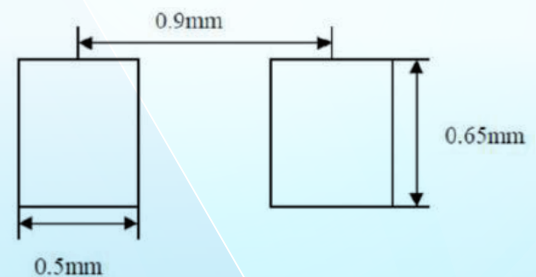
Rated Current	1.0In	2.5In	3.5In
1A~4A	4 hour min.	5 sec max.	-
200mA~750mA		-	5 sec max.

### Dimensions

Drawing not to scale (Unit:mm)



Recommended land pattern:



**Performance Specifications**

Part No.	Rated Current (A)	Rated Voltage DC	Interrupting Rating	Resistance (mOhms)**Typ	Typical Melt I <sup>2</sup> t** (A <sup>2</sup> sec)
JFC0402-0200FS	0.20	32V	35A	1750	0.0006
JFC0402-0250FS	0.25			1500	0.0010
JFC0402-0315FS	0.315			1000	0.0014
JFC0402-0375FS	0.375			780	0.0018
JFC0402-0500FS	0.50			500	0.0043
JFC0402-0750FS	0.75			220	0.011
JFC0402-1100FS	1.0			130	0.04
JFC0402-1150FS	1.5			78	0.06
JFC0402-1200FS	2.0			40	0.13
JFC0402-1250FS	2.5			24	0.20
JFC0402-1300FS	3.0			18	0.33
JFC0402-1350FS	3.5			14	0.45
JFC0402-1400FS	4.0			11	0.60

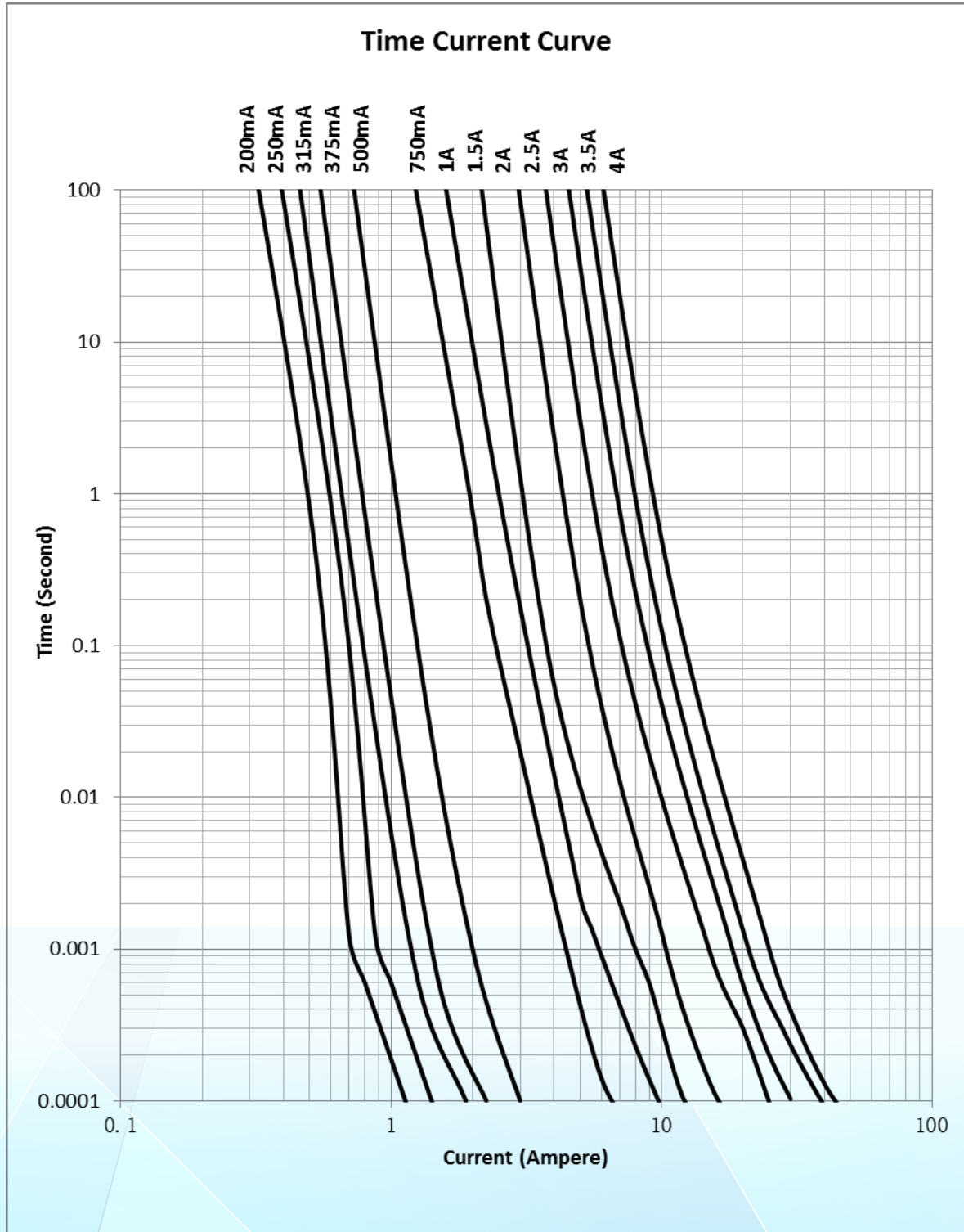
\* DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)

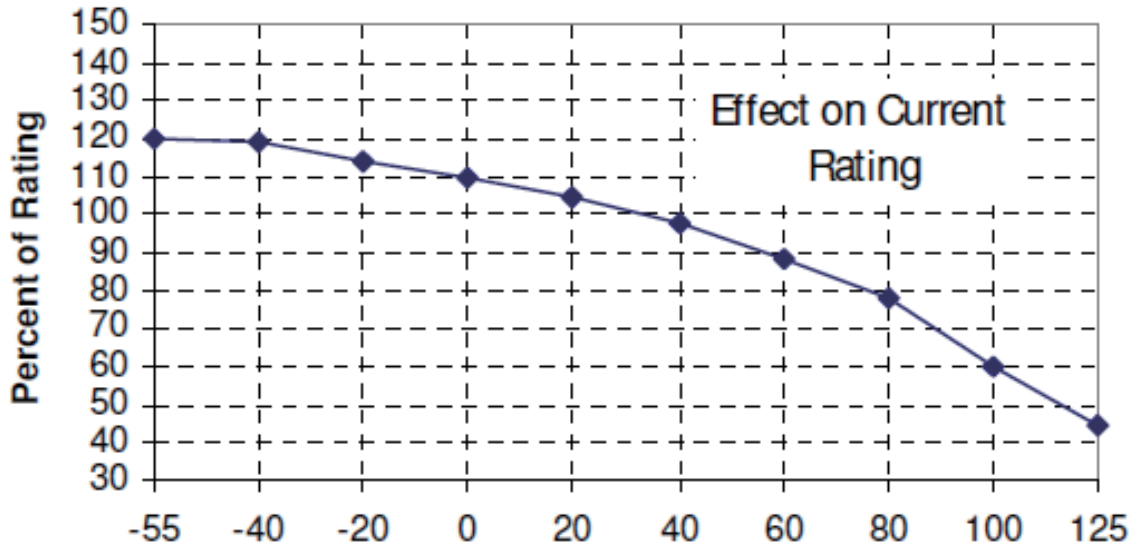
\* DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25°C

\* Typical Melting I<sup>2</sup>t (Measured with a battery bank at rated DC voltage, Measured at 1ms open time, time constant of calibrated circuit less than 50 microseconds).

\* Packing Qty: 10000

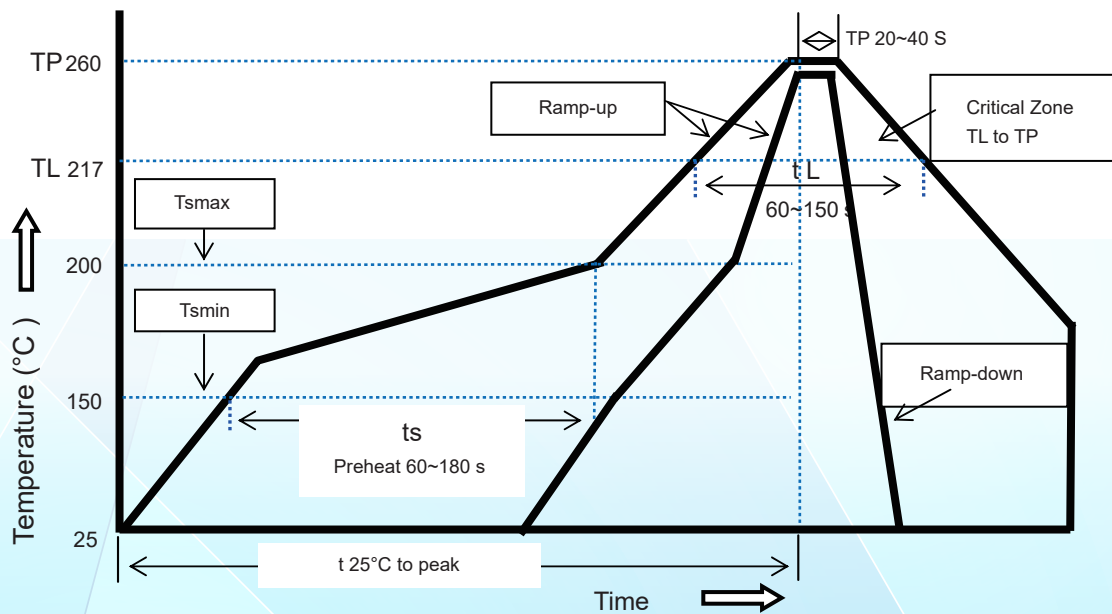
Time Current Curve



**Temperature Derating Curve**


Normal ambient temperature: 23+/-3 °C

Operating temperature: -55 ~ 125 °C, with proper correction factor applied

**Soldering Parameters**


	Reflow Condition	Pb-Free assembly
Preheating	Temperature Min Ts(min)	150 C
	Temperature Max Ts(man)	200 C
	Time Max	120 secs
Soldering	Temperature (TL)(Liquidus)	260 C
	Time Max (TL)	60 secs
	Temperature (TP)	Max 260 C
	Time Max (TP)	10 secs

### Part Numbering System

**JF C 0402 - xxxx F S**

S=SMD

T=Time-Lag, F=Fast Acting

xxxx=四位电流

0402体积

C=Ceramic, T=Thin Film, H=High Temperature Ceramic Series

JF=JDT Fuse